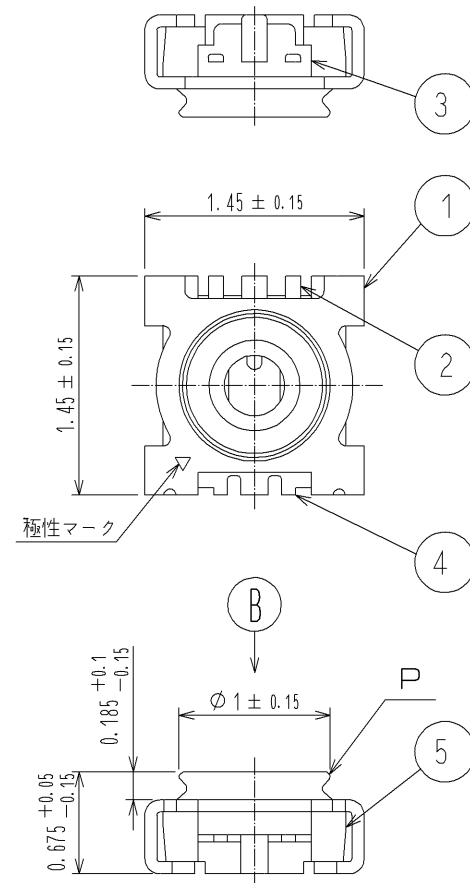
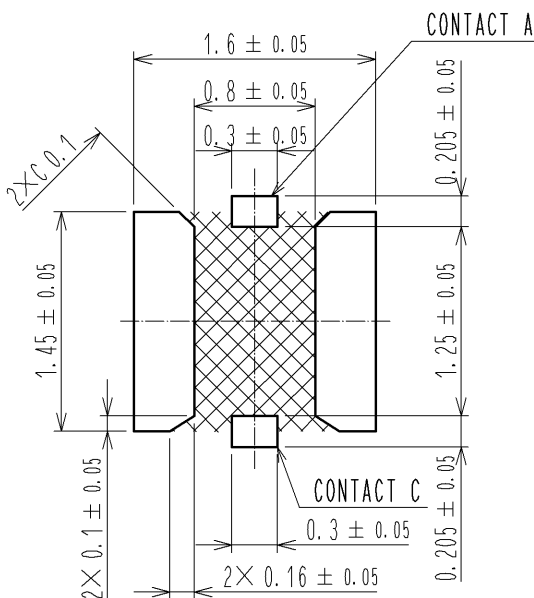
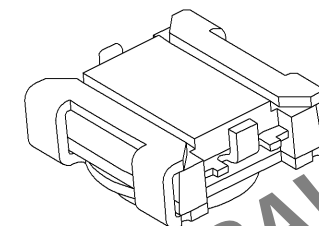
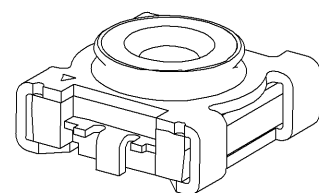
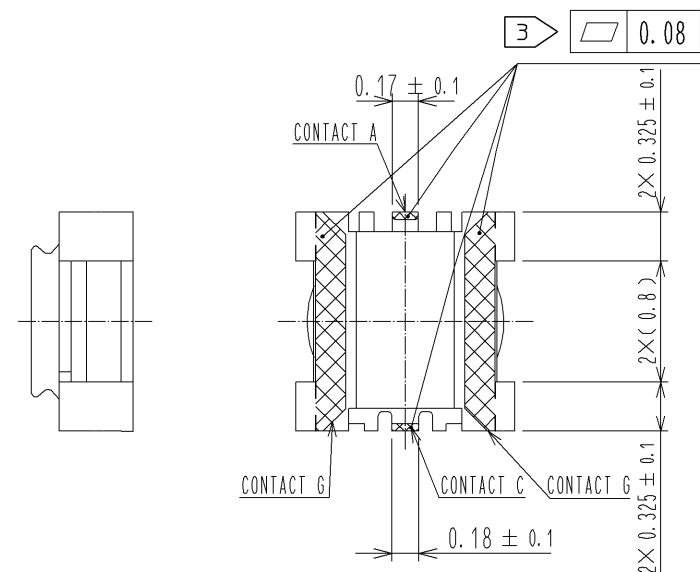




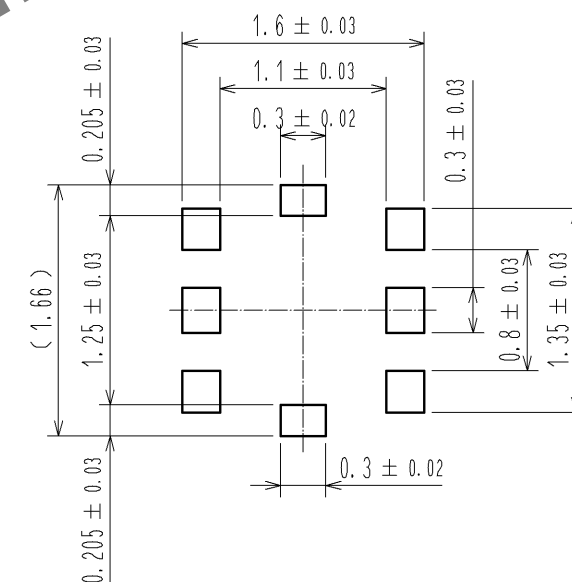
5 SPECIFIED PCB LAYOUT



:This area must be free of conductive traces and resist field.



5 SPECIFIED STENCIL PLATE THICKNESS: 0.1mm

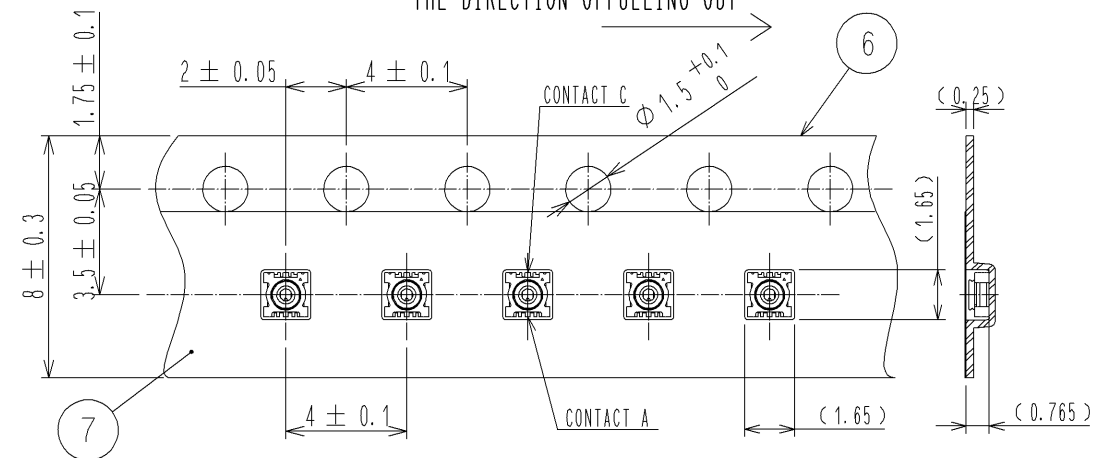


RoHS COMPLIANT

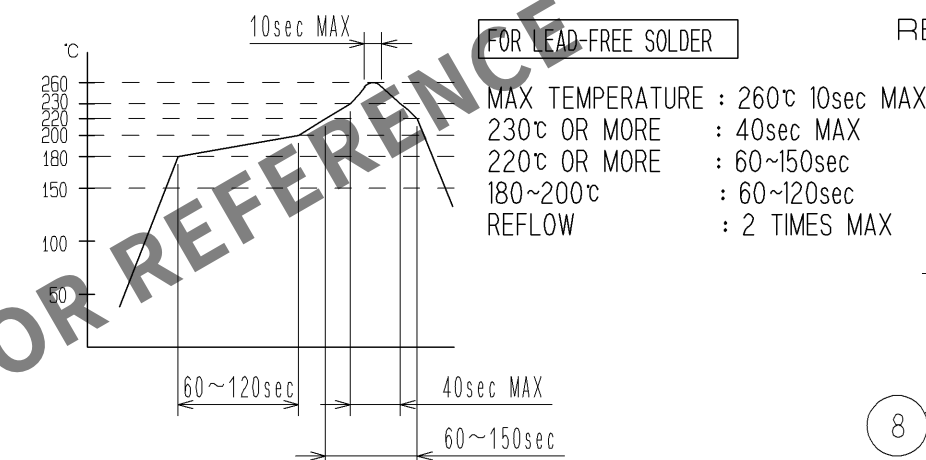
HALOGEN FREE

PACKAGING SPECIFICATION(4:1)

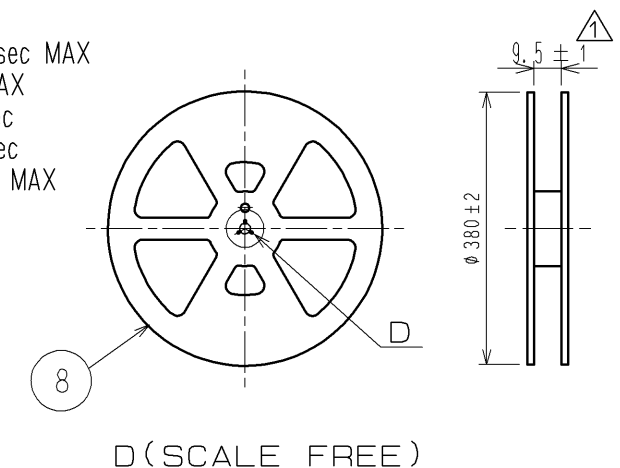
THE DIRECTION OF PULLING OUT



RECOMMENDED REFLOW TEMPERATURE PROFILE

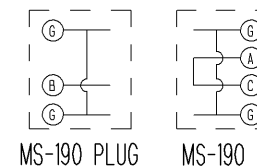


REEL DRAWING (SCALE FREE)

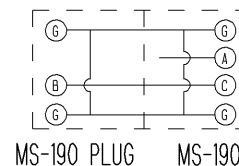


NOTE 1. Circuit shall be as follows.

STATE OF CONTACT UNMATED



STATE OF CONTACT MATED



- For use of this product, be sure to put contact area of plug on position P perpendicularly.
- Lead co-planarity is to be 0.08mm MAX.
- Do not use the washing process.
- Please do not change the specified layout of the PCB dimension and the layout of the stencil plate dimension and thickness otherwise could not be responsible for the solderability of the product.
- This product is intended to be used for circuit inspection only. Consult us if any other application is considered.
- Do not use hand soldering for mounting of MS-190.

3	LCP		8	PS	
2	CU-NI-SI-ALLOY	SELECTIVE GOLD PLATING	7	PS	
1	PHOSPHOR BRONZE	SELECTIVE GOLD PLATING	6	PS	
NO.	MATERIAL	FINISH . REMARKS	5	LCP	
NO.	MATERIAL	FINISH . REMARKS	4	CU-NI-SI-ALLOY	SELECTIVE GOLD PLATING
UNITS mm		SCALE 20 : 1	COUNT 1	DESIGNED TS. SAWAI	CHECKED MH. TSUCHIDA
APPROVED : KH. IKEDA		14. 11. 05		DRAWING NO. EDC3-360984-00	
CHECED : MH. TSUCHIDA		14. 11. 05		PART NO. MS-190	
DESIGNED : TS. SAWAI		14. 11. 05		CODE NO. CL358-0354-5-00	
DRAWN : KT. WATANABE		14. 11. 04		1/1	